### 1. General description

Trench Maximum Efficiency General Application (MEGA) Schottky barrier rectifier encapsulated in a CFP15 (SOT1289) power and flat lead Surface-Mounted Device (SMD) plastic package.

### 2. Features and benefits

- Average forward current: I<sub>F(AV)</sub> ≤ 10 A
- Reverse voltage: V<sub>R</sub> ≤ 45 V
- Low forward voltage
- Low leakage current due to Trench MEGA Schottky technology
- High power capability due to clip-bonding technology and heat sink
- Small and thin SMD plastic package, typical height 0.78 mm
- AEC-Q101 qualified

### 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Freewheeling application
- Reverse polarity protection
- Low power consumption application

### 4. Quick reference data

Table 1. Quick reference data

| Symbol         | Parameter       | Conditions  |     | Min | Тур | Max | Unit |
|----------------|-----------------|---|-----|-----|-----|-----|------|
| $V_R$          | reverse voltage | T <sub>j</sub> = 25 °C                                |     | -   | -   | 45  | ٧    |
| V <sub>F</sub> | forward voltage | I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; pulsed | [1] | -   | 480 | 545 | mV   |
| I <sub>R</sub> | reverse current | $V_R$ = 10 V; $T_j$ = 25 °C; pulsed                   | [1] | -   | 11  | 41  | μA   |
|                |                 | $V_R$ = 45 V; $T_j$ = 25 °C; pulsed                   | [1] | -   | 22  | 80  | μA   |

[1] Very short pulse, in order to maintain a stable junction temperature.



# 5. Pinning information

#### **Table 2. Pinning information**

|         | T     | Graphic symbol |
|---------|-------|----------------|
| anode   |       | K BA FA        |
| anode   |       | A aaa-009063   |
| cathode | 2     | 444 00000      |
|         | anode | anode (1)      |

# 6. Ordering information

#### **Table 3. Ordering information**

| Type number    | Package |   |         |  |  |  |
|----------------|---------|---|---------|--|--|--|
|                | Name    | Description   | Version |  |  |  |
| PMEG045T100EPD | CFP15   | plastic, thermal enhanced ultra thin SMD package; 3 terminals; 5.8 x 4.3 x 0.78 mm body | SOT1289 |  |  |  |

## 7. Marking

#### **Table 4. Marking codes**

| Type number    | Marking code |
|----------------|--------------|
| PMEG045T100EPD | 045T M10E    |

## 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol           | Parameter                           | Conditions                                       |     | Min | Max  | Unit |
|------------------|-------------------------------------|--|-----|-----|------|------|
| $V_R$            | reverse voltage                     | T <sub>j</sub> = 25 °C                           |     | -   | 45   | V    |
| l <sub>F</sub>   | forward current                     | T <sub>sp</sub> ≤ 137 °C; δ = 1                  |     | -   | 14   | Α    |
| I <sub>FSM</sub> | non-repetitive peak forward current | $t_p$ = 8 ms; $T_{j(init)}$ = 25 °C; square wave |     | -   | 130  | А    |
| P <sub>tot</sub> | total power dissipation             | T <sub>amb</sub> ≤ 25 °C                         | [1] | -   | 1.66 | W    |
|                  |                                     |  | [2] | -   | 2.15 | W    |
| T <sub>j</sub>   | junction temperature                |  |     | -   | 175  | °C   |
| T <sub>amb</sub> | ambient temperature                 |  |     | -55 | 175  | °C   |
| T <sub>stg</sub> | storage temperature                 |  |     | -65 | 175  | °C   |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

#### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

| Symbol         | Parameter  | Conditions |         | Min | Тур | Max | Unit |
|----------------|--|------------|---------|-----|-----|-----|------|
| 110-2)         | thermal resistance from junction to ambient            | -          | [1] [2] | -   | -   | 90  | K/W  |
|                |  |            | [1] [3] | -   | -   | 70  | K/W  |
| $R_{th(j-sp)}$ | thermal resistance<br>from junction to solder<br>point |            | [4]     | -   | -   | 3   | K/W  |

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.

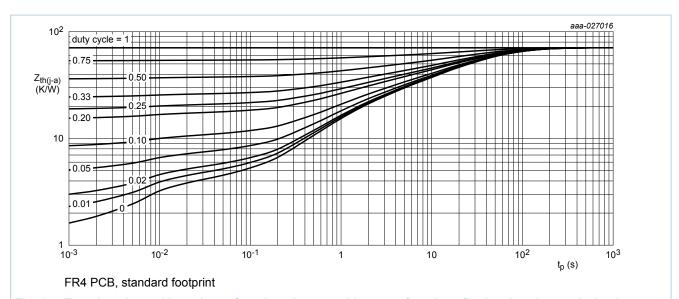


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

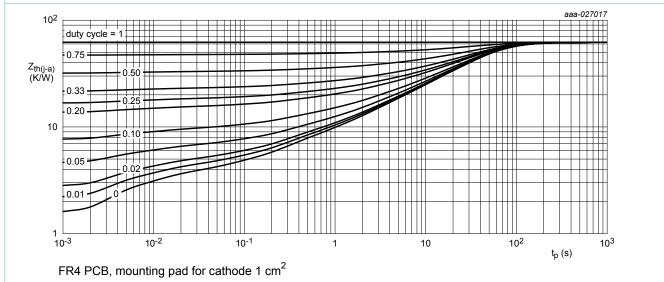


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

### 10. Characteristics

Table 7. Characteristics

| Symbol          | Parameter                           | Conditions  |     | Min | Тур | Max | Unit |
|-----------------|-------------------------------------|---|-----|-----|-----|-----|------|
| $V_{(BR)R}$     | reverse breakdown voltage           | $I_R$ = 1 mA; $T_j$ = 25 °C; pulsed   | [1] | 45  | -   | -   | V    |
| $V_{F}$         | forward voltage                     | I <sub>F</sub> = 0.1 A; T <sub>j</sub> = 25 °C; pulsed  | [1] | -   | 275 | -   | mV   |
|                 |                                     | I <sub>F</sub> = 1 A; T <sub>j</sub> = 25 °C; pulsed  | [1] | -   | 340 | 385 | mV   |
|                 |                                     | I <sub>F</sub> = 5 A; T <sub>j</sub> = 25 °C; pulsed  | [1] | -   | 415 | 475 | mV   |
|                 |                                     | I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; pulsed   | [1] | -   | 480 | 545 | mV   |
|                 |                                     | $I_F = 10 \text{ A}; T_j = -40 ^{\circ}\text{C}; \text{ pulsed}$                                  | [1] | -   | 530 | -   | mV   |
|                 |                                     | I <sub>F</sub> = 10 A; T <sub>j</sub> = 125 °C; pulsed  | [1] | -   | 380 | -   | mV   |
| I <sub>R</sub>  | reverse current                     | $V_R$ = 10 V; $T_j$ = 25 °C; pulsed   | [1] | -   | 11  | 41  | μΑ   |
|                 |                                     | $V_R = 30 \text{ V}; T_j = 25 ^{\circ}\text{C}; \text{ pulsed}$                                   | [1] | -   | 17  | -   | μΑ   |
|                 |                                     | $V_R$ = 45 V; $T_j$ = 25 °C; pulsed   | [1] | -   | 22  | 80  | μΑ   |
|                 |                                     | V <sub>R</sub> = 45 V; T <sub>j</sub> = 125 °C; pulsed  | [1] | -   | 15  | -   | mA   |
| C <sub>d</sub>  | diode capacitance                   | V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C   |     | -   | 1.4 | -   | nF   |
|                 |                                     | V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C  |     | -   | 0.6 | -   | nF   |
| t <sub>rr</sub> | reverse recovery time step recovery | $I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$<br>$T_j = 25 \text{ °C}$ |     | -   | 40  | -   | ns   |
|                 | reverse recovery time ramp recovery | $dI_F/dt = 200 \text{ A/}\mu\text{s}; T_j = 25 \text{ °C}; I_F = 6 \text{ A}; V_R = 26 \text{ V}$ |     | -   | 20  | -   | ns   |

<sup>[1]</sup> Very short pulse, in order to maintain a stable junction temperature.

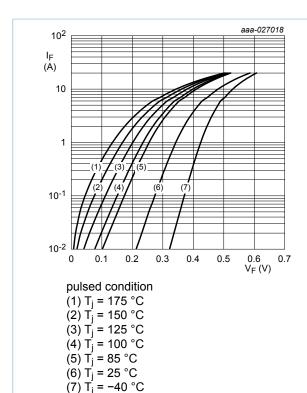


Fig. 3. Forward current as a function of forward voltage; typical values

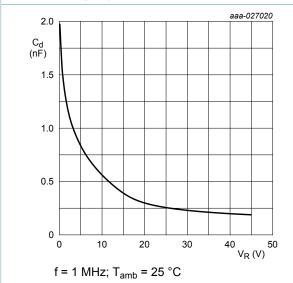


Fig. 5. Diode capacitance as a function of reverse voltage; typical values

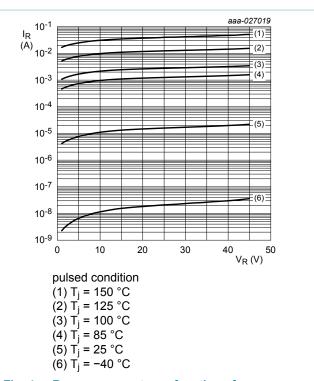
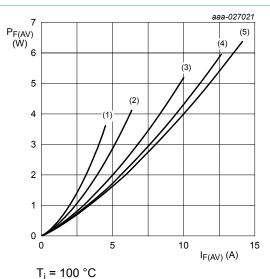


Fig. 4. Reverse current as a function of reverse voltage; typical values



(1)  $\delta = 0.1$ (2)  $\delta = 0.2$ (3)  $\delta = 0.5$ (4)  $\delta = 0.8$ (5)  $\delta = 1$ ; DC

Fig. 6. Average forward power dissipation as a function of average forward current; typical values

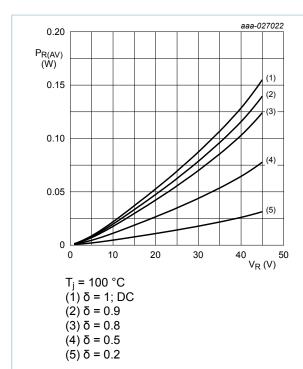
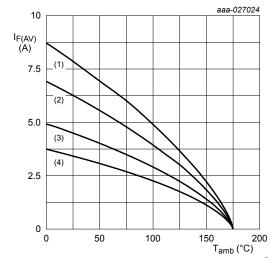


Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, mounting pad for cathode 1  $\mathrm{cm}^2$ 

 $T_j = 175 \,{}^{\circ}\text{C}$ 

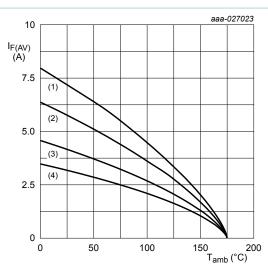
 $(1) \delta = 1; DC$ 

(2)  $\delta$  = 0.5; f = 20 kHz

(3)  $\delta$  = 0.2; f = 20 kHz

(4)  $\delta$  = 0.1; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



FR4 PCB, standard footprint

T<sub>i</sub> = 175 °C

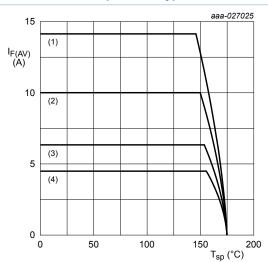
 $(1) \delta = 1; DC$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta$  = 0.2; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



 $T_i = 175 \,{}^{\circ}\text{C}$ 

 $(1) \delta = 1; DC$ 

(2)  $\delta$  = 0.5; f = 20 kHz

(3)  $\delta$  = 0.2; f = 20 kHz

(4)  $\delta$  = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

### 11. Test information

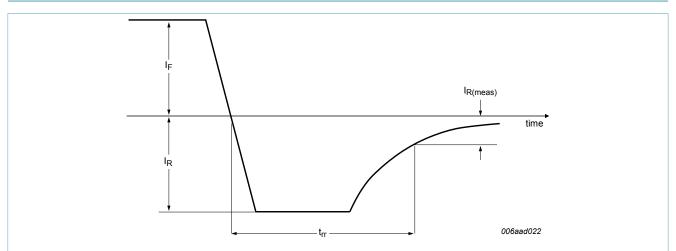


Fig. 11. Reverse recovery definition; step recovery

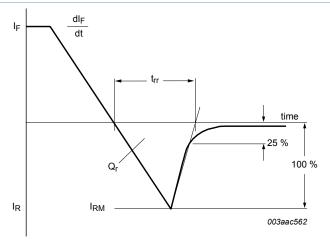


Fig. 12. Reverse recovery definition; ramp recovery

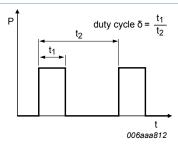


Fig. 13. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,

 $I_{RMS}$  =  $I_{F(AV)}$  at DC, and  $I_{RMS}$  =  $I_{M}$  ×  $\sqrt{\delta}$ 

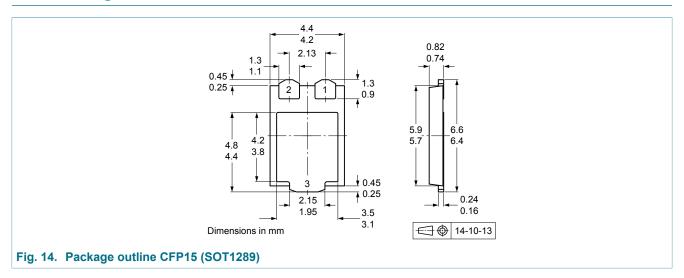
with  $I_{\mbox{\scriptsize RMS}}$  defined as RMS current.

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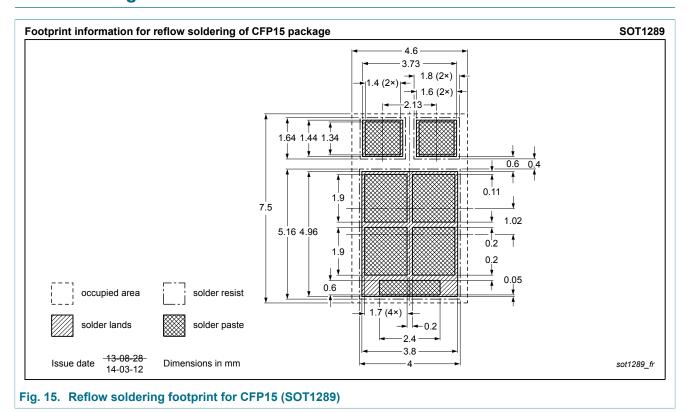
### **Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline



### 13. Soldering



# 14. Revision history

#### Table 8. Revision history

| Tubic of Iteriologic Inletery |              |                    |               |            |  |  |  |  |  |
|-------------------------------|--------------|--------------------|---------------|------------|--|--|--|--|--|
| Data sheet ID                 | Release date | Data sheet status  | Change notice | Supersedes |  |  |  |  |  |
| PMEG045T100EPD v.1            | 20170927     | Product data sheet | -             | -          |  |  |  |  |  |

## 15. Legal information

#### **Data sheet status**

| Document status [1][2]               | Product status [3] | Definition  |
|--------------------------------------|--------------------|---|
| Objective<br>[short] data<br>sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary<br>[short] data<br>sheet | Qualification      | This document contains data from the preliminary specification.                       |
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